

Appl. No : 09/933,961
Amdt. dated : 12/05/03
Reply to Office Action of 11/25/03

Amendments to the Claims:

This listing will replace all prior versions, and listing, of claims in the application.

Claims 1-3: (cancelled).

4. (currently amended) A method of creating [[a]] an electrostatic discharge free component container for storing and transporting components that are used for [[the]] manufacturing of semiconductor devices, comprising ~~the steps of:~~

providing an inner shell, said inner shell comprising polymethylmethacrylate (PPMA), said inner shell having an outer surface, said inner shell having been provided with a cavity, said inner shell having been provided with a front surface, said front surface having been provided with a means for accessing said cavity of said inner shell, said cavity having been provided with a means for positioning said component inside said cavity;

providing a metallic layer having a first and a second surface, said first and said second surface having been coated with a layer of polyimide;

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attaching said metallic layer to said outer surface of said inner shell, completely covering said inner shell with said metallic layer, creating a two layered shell having a cavity, said two layered shell further having outside surfaces, said outside surfaces of said two layered shell having first dimensions in an X, Y and Z direction;

providing an outer shell, said outer shell comprising polymethylmethacrylate (PPMA), said outer shell having a cavity, said outer shell having been provided with a front surface, said front surface having been provided with a means for accessing said cavity of said outer shell, said outer shell further having inside surfaces, said inside surfaces of said outer shell having second dimensions in an X, Y and Z direction, said second dimensions of said outer shell being essentially equal to said first dimensions of said two layered shell, thereby completely surrounding said two layered shell with said outer shell, thereby completing creation of an electrostatic discharge free container comprising a cavity that is surrounded by a compound layer of PPMA-Poly covered metal-PPMA.

5. (original) The method of claim 4, said metallic layer comprising aluminum.

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6. (original) The method of claim 1, said providing said means

for positioning said component inside said cavity comprising the steps of:

providing at least one support post having a surface in a plane, said at least one support post comprising a high-resistivity material;

providing at least one platform; and

positioning said at least one platform above said at least one support post, said at least one platform being in contact with said at least one support post, said at least one platform being positioned in said plane of said surface of said at least one support post, said at least one support post comprising a high-resistivity material.

Claims 7-12: (cancelled)

13. (currently amended) A method for creating an electrostatic discharge free component container for storing and transporting components that are used for the manufacturing of semiconductor devices, comprising ~~the steps of~~:

creating surfaces for said component container, said surfaces comprising at least two layers of high resistivity material, at least one layer of low resistivity material having

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been interspersed between said at least layers of high

resistivity material;

creating a cavity surrounded by said surfaces;

providing said cavity with a means for positioning said component inside said cavity; and

providing at least one of said surfaces of said component container with means for accessing said cavity.

14. (original) The method of claim 13, said high resistivity material comprising polymethylmethacrylate (PPMA).

15. (original) The method of claim 13, said low resistivity material comprising metal.

16. (original) The method of claim 13, said low resistivity material comprising aluminum.

17. (original) The method of claim 13, surfaces of said low resistivity material additionally being coated with polyester.

18. (original) The method of claim 13, said providing said cavity with a means for positioning said component inside said cavity comprises the steps of:

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providing at least one support post having a surface in a plane, said at least one support post comprising a high-resistivity material; and

providing at least one platform; and positioning said at least one platform above said at least one support post, said at least one platform being in contact with said at least one support post, said at least one platform being positioned in said plane of said surface of said at least one support post, said at least one support post comprising a high-resistivity material.